Special Issue

The Fabrication of Microstructures from Powders and Their Applications in Microsystems

Message from the Guest Editor

This Special Issue seeks to showcase research papers and review articles that focus on: (1) powder-based techniques for 3D microstructure fabrication compatible to silicon, glass, ceramic or plastic substrates, panels or boards; (2) simulation and characterization of powder-based 3D microstructures fabricated from various materials; (3) fabrication, simulation and characterization of MEMS devices utilizing powder-based 3D microstructures; (4) novel functionalities and applications for MEMS due to powder-based 3D microstructures; (5) durability, reliability and long-term stability of powder-based 3D microstructures.

- powder-based techniques
- 3D microstructures
- MEMS

Guest Editor

Dr. Thomas Lisec

Fraunhofer Institute for Silicon Technology ISIT, Itzehoe 25524, Schleswig-Holstein, Germany

Deadline for manuscript submissions

closed (31 December 2021)

Micromachines

an Open Access Journal by MDPI

Impact Factor 3.0
CiteScore 6.0
Indexed in PubMed

mdpi.com/si/65893

Micromachines
Editorial Office
MDPI, Grosspeteranlage 5
4052 Basel, Switzerland
Tel: +41 61 683 77 34
micromachines@mdpi.com

mdpi.com/journal/micromachines

Micromachines

an Open Access Journal by MDPI

Impact Factor 3.0
CiteScore 6.0
Indexed in PubMed

mdpi.com/journal/micromachines

About the Journal

Message from the Editor-in-Chief

You are invited to contribute research articles or comprehensive reviews for consideration and publication in *Micromachines* (ISSN 2072-666X). *Micromachines* is published in the open access format. Research articles, reviews and other contents are released on the internet immediately after acceptance. The scientific community and the general public have unlimited free access to the content as soon as it is published. As an open access journal, *Micromachines* is supported by the authors or their institutes by payment of article processing charges (APC) for accepted papers. We are pleased to welcome you as our authors.

Editor-in-Chief

Prof. Dr. Ai-Qun Liu
1. Department of Electrical and Electronic Engineering, The Hong Kong Polytechnic University, Hong Kong, China
2. School of Electrical and Electronic Engineering, Nanyang Technological University, Singapore 639798, Singapore

Author Benefits

High Visibility:

indexed within Scopus, SCIE (Web of Science), PubMed, PMC, Ei Compendex, dblp, and other databases.

Journal Rank:

JCR - Q2 (Instruments and Instrumentation) / CiteScore - Q1 (Mechanical Engineering)

Rapid Publication:

manuscripts are peer-reviewed and a first decision is provided to authors approximately 17.2 days after submission; acceptance to publication is undertaken in 1.9 days (median values for papers published in this journal in the first half of 2025).

MDPI